



Attorney Docket No.: 0254-094-CIP4-C1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Title: Memory Expansion and Chip Scale Stacking System and Method
Application No.: 10/814,530
Filing Date: 03/31/2004
Inventor: Russell Rapport, et. al.
Assignee: Staktek Group, L.P.
Examiner: TBA
Group: TBA

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Pursuant to the guidelines for Information Disclosure Statements, 37 C.F.R. §§ 1.97-1.98, attached hereto is PTO Form 1449 (six sheets) with references listed for consideration by the Office.

In accordance with 37 C.F.R. § 1.98(a), copies of the listed written references are being provided.

In accordance with 37 C.F.R. §§ 1.97(g)-(h), the filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made or an admission that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b) or prior art under 35 U.S.C. §§ 102 or 103.

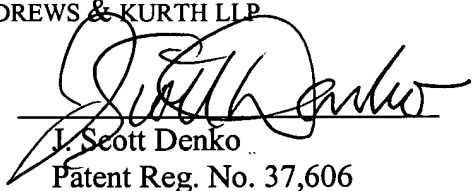
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Respectfully submitted,

ANDREWS & KURTH LLP

April 19, 2004
Date

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Form PTO-1449 (Modified)
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(37 CFR 1.306(b))

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						Yes	No
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						Yes	No
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